

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 10-189666
(43)Date of publication of application : 21.07.1998

(51)Int.Cl. H01L 21/60

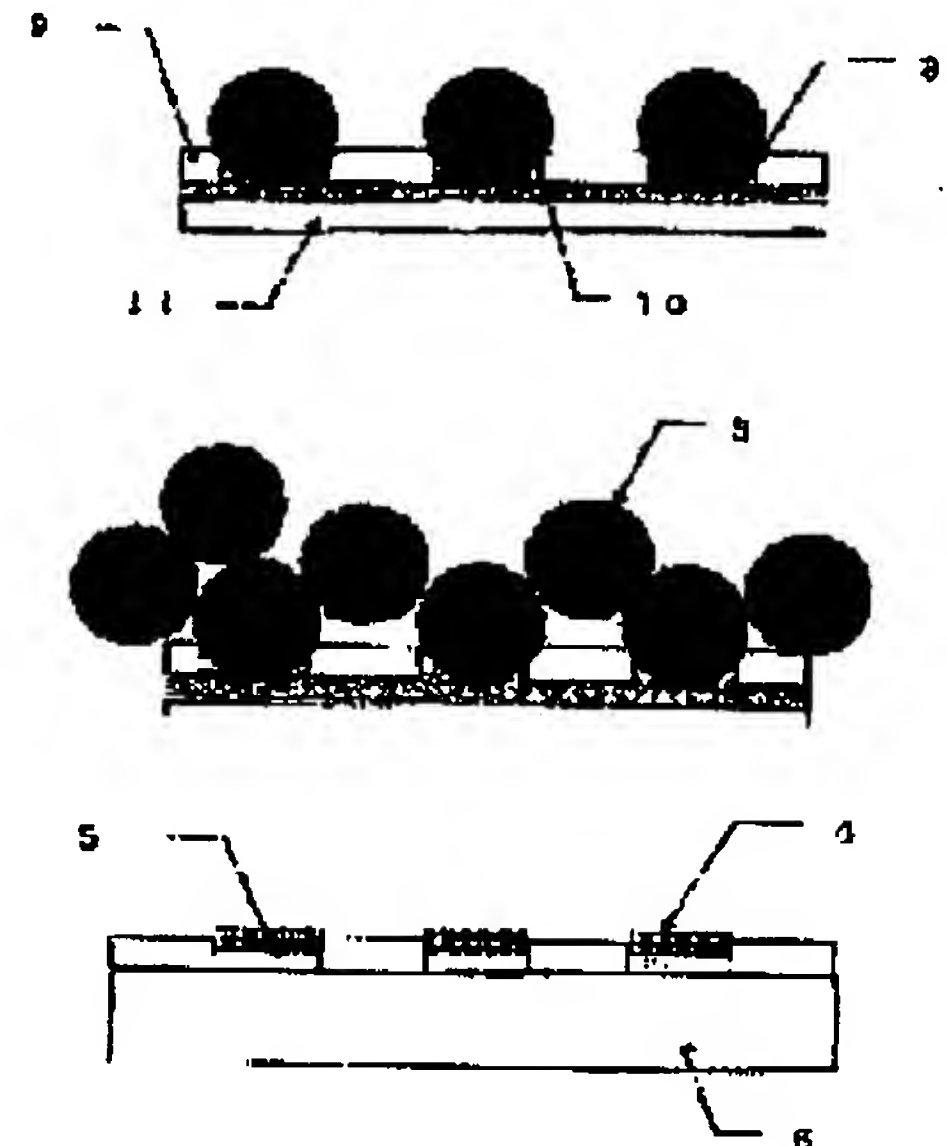
(21)Application number : 08-349927 (71)Applicant : SUMITOMO METAL MINING CO LTD
(22)Date of filing : 27.12.1996 (72)Inventor : SHIMOJI TAKUMI

(54) SOLDER BALL MOUNTING CARRIER FILM, ITS MANUFACTURE, AND SOLDER BALL-MOUNTING METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To realize a solder ball mounting carrier film where flux is not required to be precisely controlled in feed and a tool or the like is restrained from being contaminated with flux even if flux is excessively fed.

SOLUTION: A solder ball mounting operation is carried out by using a solder ball mounting carrier film composed of an adhesive tape which comprises a film 9 provided with through-holes 8, adhesive agent 10, and a base film 11 and solder balls. This solder ball mounting operation is carried out using the above solder ball mounting carrier film through such a manner that the outer pads 5 of a semiconductor package 6 are aligned with the solder balls 3 of the solder ball mounting carrier film and thermocompressed to fuse the solder balls 3. Then, the solder balls 3 are cooled below the melting point, whereby the solder balls 3 are fixed to the outer pads 5. Thereafter, the above carrier film is peeled off to transfer the solder balls 3 onto the outer pads 5.



LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]